



Process Flow Chart for Rigid-flex PCB

1.1. Flex inner layer DES (Develop, Etch & Strip)

1.2. Flex inner layer Coverlay Bonding

1.3. Rigid inner layer DES

2. Rigid-Flex Lay-Up

3. Lamination

4. X-Ray Drilling

5. Drilling

6. Desmear, PTH & Panel Plating

7. Outer layer Dry Film

8. Develop, Etch & Strip (DES)

9. AOI Inspection

10. Solder Mask

11. Silkscreen

12. Surface treatment (Immersion Gold/OSP)

13. Routing (Profiling)

14. Electrical Test

15. Packing